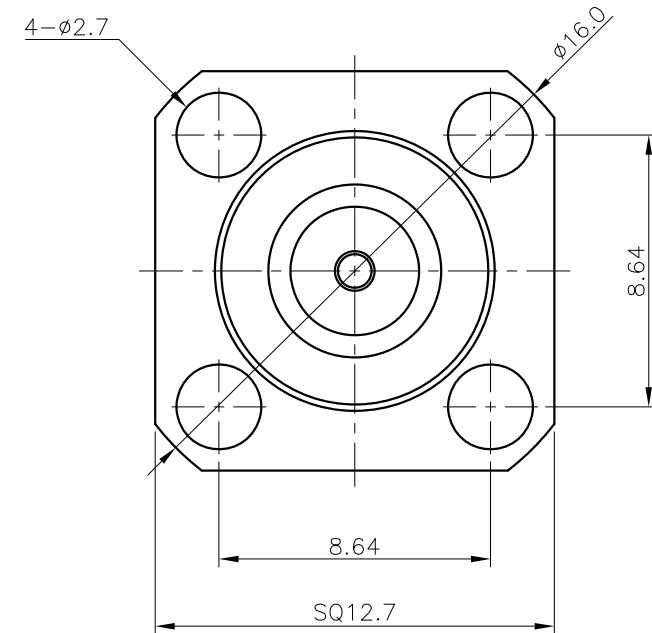
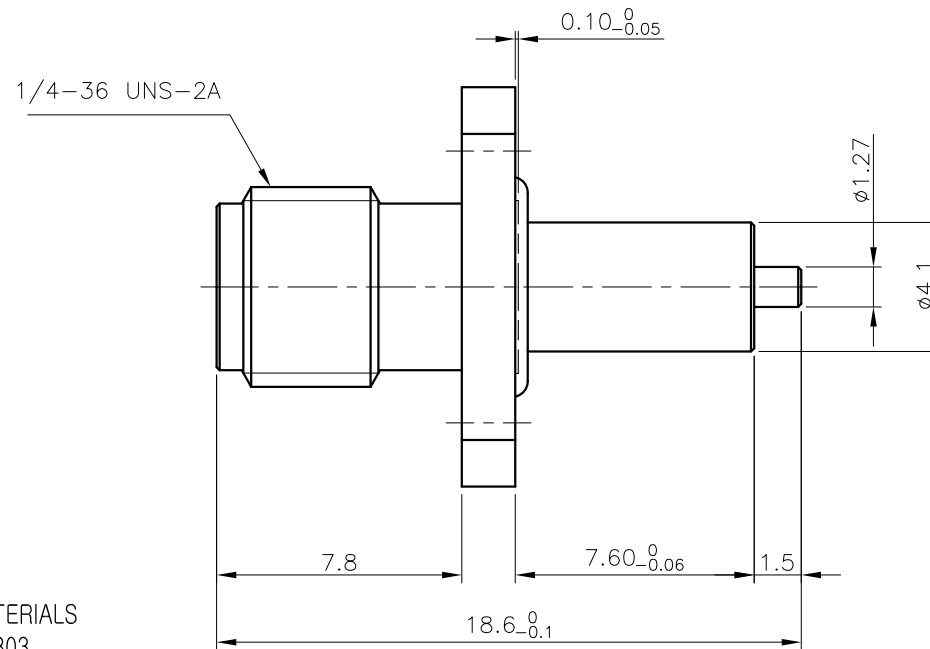


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2019.11.06.



Notes

- RoHS & Pb-FREE
- CONNECTOR MATERIALS
 - BODY : SUS303
CONTACT : Beryllium copper
INSULATOR : TEFLON
GASKET : SILICONE RUB
- ELECTRICAL
 - IMPEDANCE : 50Ohm
 - FREQ. RANGE : DC to 6GHz
 - VSWR (Max) : 1.2
 - INSERTION LOSS : 0.07 √F(GHz) dB MAX
 - RF LEAKAGE : -(80 -F(GHz) dB MAX
 - VOLTAGE RATING : 350 VEFF MAX
 - DIELECTRIC WITHSTANDING VOLTAGE : 1000 VEFF MIN
 - INSULATION RESISTANCE : 5000 MOHMS MIN
- MECHANICAL
 - RECOMMENDED COUPLING NUT TORQUE : 0.8Nm ~ 1.1Nm
 - COUPLING NUT RETENTION FORCE : ≥270N
- ENVIRONMENTAL
 - TEMPERATURE RANGE : -65° ~ +165°C

4	INSULATOR	1	TEFLON		DIN01500-N/1
3	GASKET	1	SILICONE RUB		DGK00020-N/1
2	CONTACT	1	BeCu C17300	Gold Plate (1.27μm)	DCT03845-5/2
1	BODY	1	SUS303	Passivate	DBD04572-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2019. 11. 06.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY I.C.KIM				
MATERIAL —		CHECKED BY		TITLE SMA50 SOLDER END JS-4H		
		DRAWN BY S.Y.EUN				
FINISH —		SCALE 4/1	UNIT mm		A4	DWG NO. CN03891-7/1
						REVISION I R